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Certification

Hewlett-Packard Company certifies that this product met its published specifications at the time of shipment from the factory. Hewlett-Packard further certifies that its calibration measurements are traceable to the United States National Institute of Standards and Technology (formerly National Bureau of Standards), to the extent allowed by that organization's calibration facility, and to the calibration facilities of other International Standards Organization members.

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Documentation History

All Editions and Updates of this manual and their creation date are listed below. The first Edition of the manual is Edition 1. The Edition number increments by 1 whenever the manual is revised. Updates, which are issued between Editions, contain replacement pages to correct or add additional information to the current Edition of the manual. Whenever a new Edition is created, it will contain all of the Update information for the previous Edition. Each new Edition or Update also includes a revised copy of this documentation history page.

Edition 1	 	 	 	 			 	 				 		 .June	1	997
Edition 2	 	 	 	 			 	 		 		 		 .May	1	998

Safety Symbols



Instruction manual symbol affixed to product. Indicates that the user must refer to the manual for specific WARNING or CAUTION information to avoid personal injury or damage to the product.

Indicates the field wiring terminal that must be connected to earth ground before operating the equipment Aprotects against

electrical shock in case of fault.



Alternating current (AC)



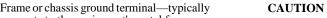
Direct current (DC).



Indicates hazardous voltages.



Calls attention to a procedure, practice, or condition that could cause bodily injury or death.



Calls attention to a procedure, practice, or condition that could possibly cause damage to equipment or permanent loss of data.

WARNINGS

connects to the equipment's metal frame.

The following general safety precautions must be observed during all phases of operation, service, and repair of this product. Failure to comply with these precautions or with specific warnings elsewhere in this manual violates safety standards of design, manufacture, and intended use of the product. Hewlett-Packard Company assumes no liability for the customer's failure to comply with these requirements.

Ground the equipment: For Safety Class 1 equipment (equipment having a protective earth terminal), an uninterruptible safety earth ground must be provided from the mains power source to the product input wiring terminals or supplied power cable.

DO NOT operate the product in an explosive atmosphere or in the presence of flammable gases or fumes.

For continued protection against fire, replace the line fuse(s) only with fuse(s) of the same voltage and current rating and type. DO NOT use repaired fuses or short-circuited fuse holders.

Keep away from live circuits: Operating personnel must not remove equipment covers or shields. Procedures involving the removal of covers or shields are for use by service-trained personnel only. Under certain conditions, dangerous voltages may exist even with the equipment switched off. To avoid dangerous electrical shock, DO NOT perform procedures involving cover or shield removal unless you are qualified to do so.

DO NOT operate damaged equipment: Whenever it is possible that the safety protection features built into this product have been impaired, either through physical damage, excessive moisture, or any other reason, REMOVE POWER and do not use the product until safe operation can be verified by service-trained personnel. If necessary, return the product to a Hewlett-Packard Sales and Service Office for service and repair to ensure that safety features are maintained.

DO NOT service or adjust alone: Do not attempt internal service or adjustment unless another person, capable of rendering first aid and resuscitation, is present.

DO NOT substitute parts or modify equipment: Because of the danger of introducing additional hazards, do not install substitute parts or perform any unauthorized modification to the product. Return the product to a Hewlett-Packard Sales and Service Office for service and repair to ensure that safety features are maintained.

Declaration of Conformity

according to ISO/IEC Guide 22 and EN 45014

Manufacturer's Name: Hewlett-Packard Company

Loveland Manufacturing Center

Manufacturer's Address: 815 14th Street S.W.

Loveland, Colorado 80537

declares, that the product:

Product Name: Double-Wide Breadboard M-Module

Model Number: HP E2259A

Product Options: All

conforms to the following Product Specifications:

Safety: IEC 1010-1 (1990) Incl. Amend 2 (1996)/EN61010-1 (1993)

CSA C22.2 #1010.1 (1992)

UL 3111-1 (1994)

EMC: CISPR 11:1990/EN55011 (1991): Group1 Class A

EN61000-3-2:1995 Class A

EN50082-1:1992

IEC 801-2:1991: 4kV CD, 8kV AD

IEC 801-3:1984: 3 V/m

IEC 801-4:1988: 1kV Power Line, 0.5kV Signal Lines

ENV50141:1993/prEN50082-1 (1995): 3 Vrms

ENV50142:1994/prEN50082-1 (1995): 1 kV CM, 0.5 kV DM

IEC1000-4-8:1993/prEN50082-1 (1995): 3 A/m

EN61000-4-11:1994/prEN50082-1 (1995): 30%, 10ms 60%, 100ms

Supplementary Information: The product herewith complies with the requirements of the Low Voltage Directive 73/23/EEC and the EMC Directive 89/336/EEC (inclusive 93/68/EEC) and carries the "CE" mark accordingly.

Tested in a typical configuration in an HP C-Size VXI mainframe.

April 7, 1997

Jim White, Quality Manager

European contact: Your local Hewlett-Packard Sales and Service Office or Hewlett-Packard GmbH, Department HQ-TRE, Herrenberger Straße 130, D-71034 Böblingen, Germany (FAX: +49-7031-14-3143)

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Reader Comment Sheet

HP E2259A Double-Wide Breadboard M-Module User's Manual and Programming Guide Edition 2

You can help us improve our manuals by sharing your comments and suggestions. In appreciation of your time, we will enter you in a quarterly drawing for a Hewlett-Packard Palmtop Personal Computer (U.S. government employees are not eligible for the drawing).

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Chapter 1 Getting Started

What's in this Manual?

This manual contains a module description, configuration and wiring information, and general programming information for the HP E2259A Double-Wide Breadboard M-Module. Complete specifications for the breadboard are provided in Appendix A.

The HP E2259A is intended to be installed on a carrier such as the HP E2251 M-Module Carrier. Refer to the Carrier documentation for M-Module installation information.

This chapter contains general features, a block diagram description, configuration information and connector pinouts for the HP E2259A.

Module Description

The HP E2259A is a double-wide breadboard M-Module. As a double-wide module it occupies two adjacent slots in the Carrier. However, it is scored down the middle and can easily be "snapped" in half; with all the active M-Module interface circuits on one of the two halves. See Figure 1-2.

Even though the HP E2259A breadboard is a double-wide, in an HP E2251 Carrier, the module requires only one VXIbus logical address. When installed in the Carrier the module functions as a standard VXIbus device.

General Features The

The HP E2259A provides:

- A8/D16 Register-based M-Module interface circuitry.
- A programmable BUSY Timer (for delaying interrupt acknowledgment of command completion).
- A 16-bit input/output (I/O) Register.
- Read/Write decoder lines
- Support for internal/external interrupts.

Block Diagram Description

Figure 1-1 shows a simplified block diagram of the HP E2259A. In order to effectively program the module you must understand its operation at a block diagram level. The following paragraphs describe the major sections in the block diagram.

Module Control

This block contains all of the logic for the module including carrier interface, registers, interrupt control, the programmable busy timer, I/O lines, control lines, etc. All lines except the latched data output lines (BC0 -BC15) connect directly to the U101 controller FPGA.

The I/O register at 14H in A24 memory space is realized on this Breadboard. Writing to this register automatically outputs the data on the BC0 - BC15 lines; similarly, reading this register automatically reads the data on the TRO - TR15 lines. More I/O registers can be expanded by using the decoder lines and additional circuits.

ID EEPROM

The ID EEPROM holds sixty-four 16-bit words of M-Module ID data and VXI M-Module data.

Input and Output Circuit

The breadboard data input lines (TR0 - TR15) connect directly from the J103 pads to the U101 controller FPGA. The data output lines (BC0 - BC15) are latched by U107 and U108 (74ACTQ273SM) and are available on J103. Control lines (LAT*, DBEN*, CRST*, etc.) and the I/O Decoder lines (WPO - WP7 for write decoder lines and RP0 - RP7 for read decoder lines) are available on J102. Refer to Chapter 2 for information on using these lines.

Power Supplies

The HP E2259A Breadboard provides filtered ±12VDC and +5VDC supplies for use on the breadboard. Do not exceed the maximum current specifications for the breadboard (see Appendix A). The active electronics provided on the module use only the +5VDC supply.

Each power supply is protected by a positive-temperature-coefficient thermistor. When maximum current through the thermistor is reached, its resistance increases significantly thereby limiting the current; the thermistor acts like a resettable fuse. Table 1-1 lists the power supplies, thermistor protection reference designator (silkscreened on PC board), and the maximum current.

Table 1-1. HP E2259A Power Supply Protection

	Thermistor Ref. Designator	Maximum Current
+5VDC Supply	F201	1000mA
+12VDC Supply	F200	200mA
-12VDC Supply	F202	200mA

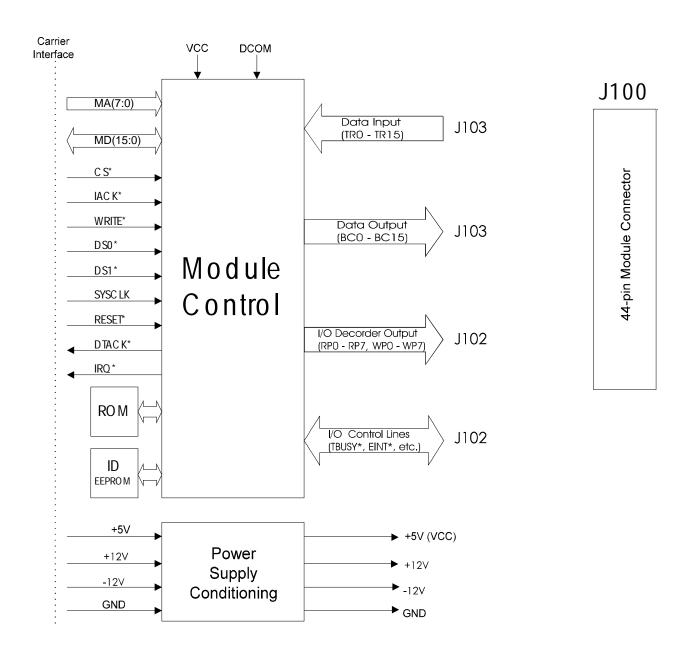


Figure 1-1. HP E2259A Block Diagram

Configuring the Module

This section provides general information to connect user wiring to the breadboard module and provides guidelines for mounting components on the module.

Note

This section does not describe installing the breadboard module in a carrier. Since installation is dependent on the carrier used, you should refer to your carrier's documentation for detailed installation instructions. Each HP M-Module is supplied with identifying labels that should be installed on the carrier.

WARNING

SHOCK HAZARD. Only qualified, service-trained personnel aware of the hazards involved should install, configure, or remove the M-Module. Disconnect all power sources from the mainframe, the terminal module and installed modules before installing or removing a module.

Caution

VOLTAGE/CURRENT. Pay careful attention to the limitation of maximum voltage/current and maximum power listed in Appendix A. Exceeding any limit or use outside the parameters specified may damage the module and/or carrier.

Caution

STATIC ELECTRICITY. Static electricity is a major cause of component failure. To prevent damage to the electrical components on an M-Module or the carrier, observe anti-static techniques whenever installing, removing, or working on a carrier or M-Module.

Connectors and Access Pads Description

There are several connectors and access pads on the HP E2259A Breadboard. Refer to Figure 1-2. Connector P100 provides the carrier interface to the active electronics on the module. Connector P101 provides access to the carrier interface; all pins on P101 are mapped to access pads on P102 (refer to P100, P101, and P102 Pin Assignment on page 16 for detailed pinout). Access pads J102 and J103 provide access to the buffered input and output lines, read and write decoder lines, busy line, and power supply connections (refer to J102 and J103 Pin Assignment on page 15 for detailed pinout). Connectors J100 and J104 provide connections for user field wiring. J100 directly maps pin-for-pin to access pads on J101; J104 maps pin-for-pin to access pads on J105. Figure 1-2 also shows the maximum component height above the board and maximum lead length below the board.

Note

Observe the component height restrictions for Regions A and B on the Breadboard. Region A: 0.21 in (5.3mm); Region B: 0.42 in (10.5mm).

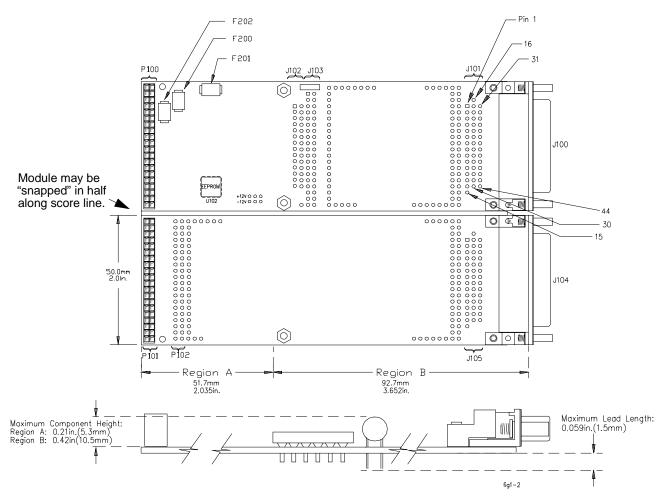


Figure 1-2. HP E2259A Connectors Layout

J100, J101, J104, and J105 **Pin Assignment**

J100, J101, J104, and J105 are for user field wiring. J100 maps pin-for-pin to J101 (see Figure 1-2) and J104 maps pin-for-pin maps to J105. Figure 1-3 shows the 44-pin field wiring connector pinout. Figure 1-6 shows how to assemble the field wiring connector and hood assembly.

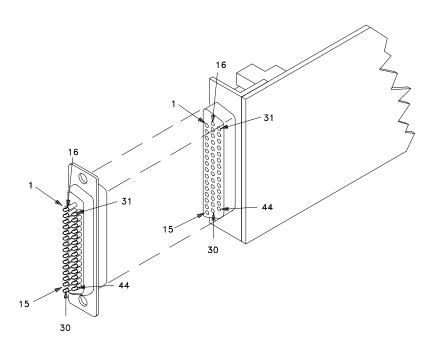
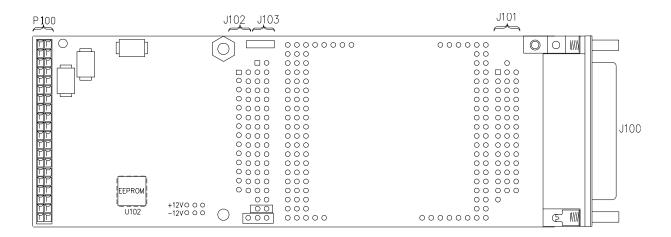


Figure 1-3. 44-Pin Field Wiring Connector

J102 and J103 Pin Assignment

Figure 1-4 shows the pinout for the J102 and J103 pads. Notice that the bottom row of pads on J103 (CGND) are connected to chassis ground through the carrier to the VXIbus mainframe. The ± 12 VDC pads are located just to the left of the bottom of J102.



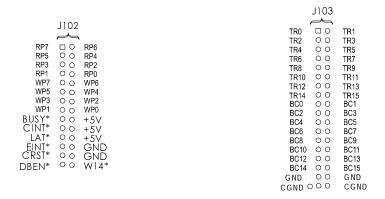


Figure 1-4. J102, J103 Connector Pinouts

TR0 - TR15: Data Input Lines (register address 14_h in A24 Memory).

BC0 - BC15: Data Output Lines (register address 14_h in A24 Memory).

WP0 - WP7: Write Decoder Lines (address 20_h-2E_h in A24 Memory).

RP0 - RP7: Read Decoder Lines (address 20_h-2E_h in A24 Memory).

BUSY*: Delay Timer Output. (Delay Time Reg. Addr. 12_h in A24) output from breadboard.

CINT*: Clear Interrupt. A negative pulse is asserted during interrupt acknowledge if external interrupt request is pending, output from breadboard.

EINT*: User Supplied External Interrupt Request. Falling edge causes interrupt to host controller if enabled.

LAT*: Latch signal for write cycle, output from breadboard.

CRST*: Reset, low means breadboard being reset, output from breadboard.

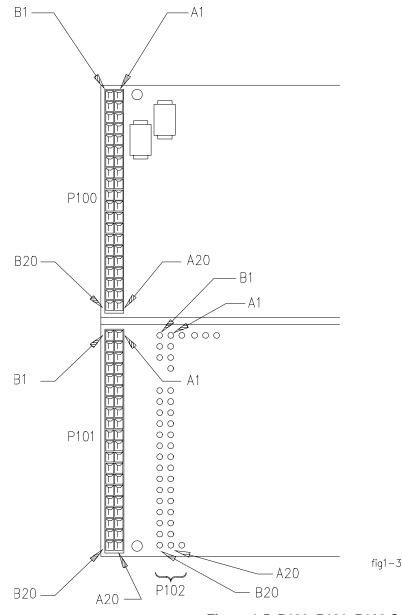
DBEN*: Data Bus Enable, low to enable data bus, output from breadboard.

W14*: Output Register Latch Signal of 14H in A24 memory space, rising edge latches data into external device, output from breadboard.

CGND: Chassis Ground

P100, P101, and P102 Pin Assignment

Figure 1-5 shows the connector pinouts for P100, P101, and P102. Pin 101 connects to and maps pin-for-pin to P102. The pin names are described on the next page.



Pin	Col A	Col B		
1	CS*	Ground		
2	MA01	+5V		
3	MA02	+12V		
4	MA03	-12V		
5	MA04	Ground		
6	MA05	DREQ*		
7	MA06	DACK*		
8	MA07	Ground		
9	MD08	MD00		
10	MD09	MD01		
11	MD10	MD02		
12	MD11	MD03		
13	MD12	MD04		
14	MD13	MD05		
15	MD14	MD06		
16	MD15	MD07		
17	DS1*	DS0*		
18	DTACK *	WRITE*		
19	IACK*	IRQ*		
20	RESET*	SYSCLK		

Figure 1-5. P100, P101, P102 Connectors

MA01 to MA07: M-Module Address Bus, Input to M-Module.

CS*: Card Select Signal, Input to M-Module. Low when the

M-Module is being accessed.

MD00 to MD15: M-Module Data Bus, Input / Output.

DACK*: Low when carrier is performing a DMA transfer, Input

to M-Module.

DREQ*: Low to requests a DMA transfer, Output from

M-Module.

DS0* - DS1*: Data Strobe Signal, Input to M-Module

00 = 16 bit data transfer 01 = D15 - D08 transfer 10 = D7 - D0 transfer 11 = no data transfer.

DTACK*: Data Acknowledge Signal, Output from M-Module.

Low to acknowledge data transfer and terminate access.

IACK*: Interrupt Acknowledge Signal, Input to M-Module.

Low when interrupt is being acknowledged.

IRQ*: Interrupt Request Signal, Output from M-Module. Low

to request an interrupt.

RESET*: System Reset Signal, Input to M-Module. Low to reset

the module.

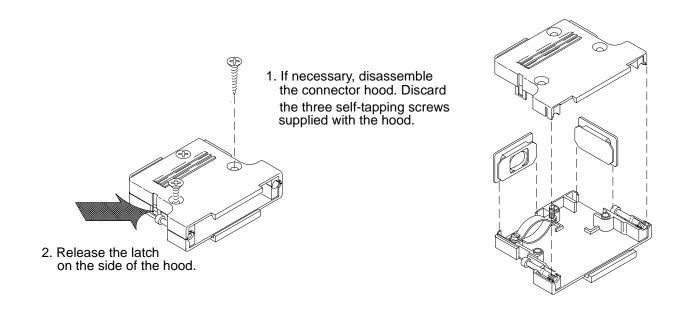
SYSCLK: 16MHz System Clock, Input to M-Module.

WRITE*: Write Signal, Input to M-Module. Low during writing

cycle, high during reading cycle.

Assembling the Field Wiring Connector

Each HP E2259A module includes two 44-pin connector and hood kits (HP kit part number E2273-01203). You must supply your own cable. The drawing below shows how to connect wiring and assemble the connector and hood.



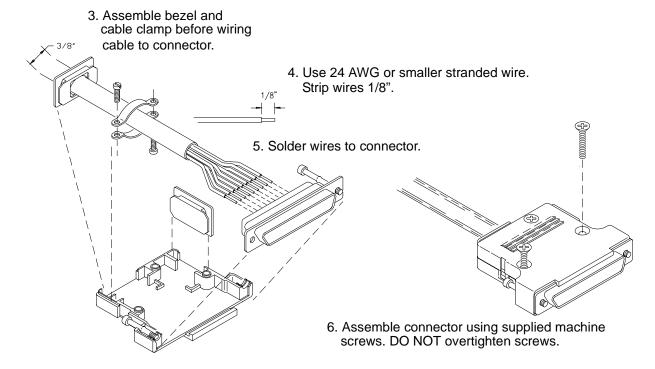


Figure 1-6. Assembling the Field Wiring Connector and Hood

Chapter 2

Using the Breadboard

What's in This Chapter

This chapter provides general operating information for the HP E2259A Double-wide Breadboard. It also provides a simple application example. The chapter contents include:

• Writing Data to Output Registers	Page 20
• Reading Data from Input Registers	Page 22
• Using the Interrupt	Page 24
• Resetting the Module	Page 28
• Using the Power Supplies	Page 28
• Application Example	Page 29

Registers

Table 2-1 lists the registers available on the HP E2259A Breadboard (Chapter 3 provides a detailed description of all of the registers on the HP E2259A.) This section provides information on using the Input/Output Register and the Read/Write Decoder Registers.

Table 2-1. HP E2259A Registers

Register Name	Register Address	Register Description
VXI ID Register	00 _h in VXI A16 Memory	Provides Device Class and Manufacturer ID.
VXI Device Type Register	02 _h in VXI A16 Memory	Provides Model Code for M-Module.
VXI Status/Control Register	04 _h in VXI A16 Memory	Controls Reset and Provides module Status information.
A24 Offset Register	06 _h in VXI A16 Memory	Provides A24 Offset Base Address.
Interrupt Selection Register	20 _h in VXI A16 Memory	Selects VXI Interrupt Line.
Status Register	00 _h in VXI A24 Memory	Selects Interrupt Source.
Control Register	02 _h in VXI A24 Memory	Controls Reset and Enables/Disables Interrupt.
Interrupt Register	04 _h in VXI A24 Memory	Selects Type of Interrupt.
Delay Timer (BUSY) Register	12 _h in VXI A24 Memory	Sets Delay Value for Command completion interrupt.
Input/Output Register	14 _h in VXI A24 Memory	Data Input from TR0 - TR15 Lines. Data Output to BC0 - BC15 Lines.
Read/Write Decoder Registers	20 _h - 2E _h in VXI A24 Memory	Used to select the latches or buffers supplied by users.

Writing Data to Output Registers

To output data over the data bus lines (BC0 - BC15), write the data to the I/O register at 14_h in A24 Memory. Figure 2-1 shows the timing of writing data to the I/O register. You only have access to the DBEN*, LAT*, W14*, and BUSY* control lines; the other control line waveforms (SYSCLK, DS0*, DS1*, CS*, DTACK*, and MA0-MA7) are provided for reference information only. Note:

- W14* has the same timing as LAT* when writing to 14H in A24 memory space.
- IRQ* is asserted at the end of the BUSY cycle (see "Using the Interrupt" on page 24). The BUSY* line pulse lasts 13mS if the module default is used. You can change the BUSY time by writing a value to the Delay Timer Register at address 12_h. Refer to Chapter 3 for details.
- MD15-MD0 are latched to BC15-BC0 at the rising edge of W14*.

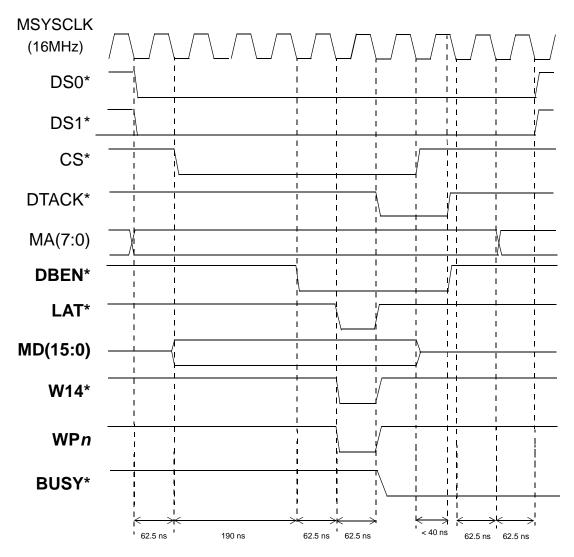


Figure 2-1. Timing of Writing to I/O Register

Using the Write Decoder Lines

You can use the eight Write Decoder lines (WP0 - WP7) as latch select lines to expand for more output registers. Table 2-2 lists the Read/Write Decoder Register Addresses and the corresponding WP and RP lines.

Table 2-2. Read/Write Decoder Lines and Register Addresses

WP / RP Line	Register Address	WP / RP Line	Register Address
WP0/ RP0	20 _h in A24 Memory	WP4 / RP4	28 _h in A24 Memory
WP1 / RP1	22 _h in A24 Memory	WP5 / RP5	2A _h in A24 Memory
WP2 / RP2	24 _h in A24 Memory	WP6 / RP6	2C _h in A24 Memory
WP3 / RP3	26 _h in A24 Memory	WP7 / RP7	2E _h in A24 Memory

Figure 2-1 shows the timing required to write output data using one of the Read/Write Decoder Registers and the corresponding WP Line. You only have access to the DBEN*, LAT*, WPn, and BUSY control lines; the other control line waveforms (SYSCLK, DS0*, etc.) are provided for reference information only.

- WP*n* has the same timing as LAT* when writing to the corresponding register address.
- There is no BUSY signal when writing to addresses other than 14H in A24 memory space.
- MD15-MD0 are latched to latches on the rising edge of WPn.

Figure 2-2 shows an example of using the WP0 Decoder Line to serve as a device latch signal.

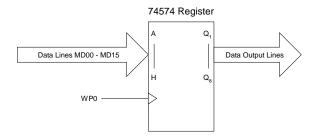


Figure 2-2. Using the Write Decoder Line WP0

To create an expanded register, write a data value to the appropriate Read/Write Decoder Register. For example, to use the circuit in Figure 2-2, you would write a 16-bit data value to the WP0 register (address 20_h in A24 memory).

Reading Data From Input Registers

To read data from the TR0 - TR15 Data Input lines, read the data from the I/O register at 14_h in A24 memory space. Figure 2-3 illustrates the timing required for reading data from this register on the HP E2259A Breadboard. You only have access to the DBEN* and LAT* control lines; the other control line waveforms are provided for reference information only.

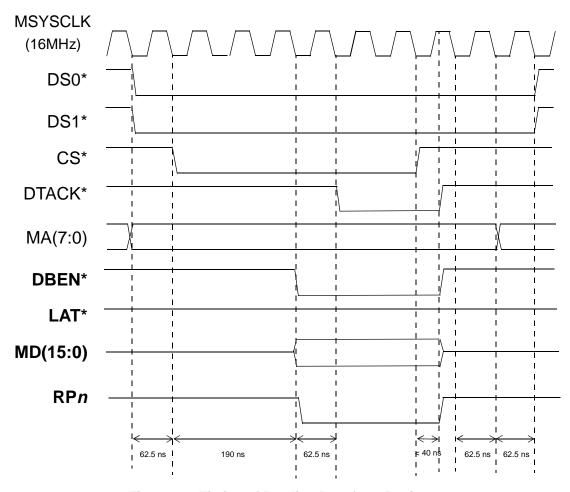


Figure 2-3. Timing of Reading Data from Registers

Using the Read Decoder Lines

Expanding input registers with read decoder lines RP0-RP7 is similar to expanding output registers (see Figure 2-2 on Page 21), except that a buffer (74245) is used as an input buffer, RPn is used as a buffer enable signal, data direction is toward MD15-MD0. The RPn lines can be used as select lines to specify which device the data is read from. Figure 2-3 also shows the timing of the RPn pulse. Table 2-3 lists the Read/Write Decoder Register Addresses and the corresponding WP and RP lines.

Table 2-3. Read/Write Decoder Lines and Register Addresses

WP / RP Line	Register Address	WP / RP Line	Register Address
WP0/ RP0	20 _h in A24 Memory	WP4 / RP4	28 _h in A24 Memory
WP1 / RP1	22 _h in A24 Memory	WP5 / RP5	2A _h in A24 Memory
WP2 / RP2	24 _h in A24 Memory	WP6 / RP6	2C _h in A24 Memory
WP3 / RP3	26 _h in A24 Memory	WP7 / RP7	2E _h in A24 Memory

Using the Interrupt

The Breadboard has a read only Interrupt Register located at address 04_h in A24 Memory. The contents of this register is used as an interrupt vector to determine which interrupt source caused the interrupt.

If IACK* (Type C interrupt) is present, the content of the Interrupt Register will be sent to the data bus and the IRQ* line will be released. Reading the Interrupt Register will clear the interrupt request signal IRQ* to support Type A interrupt.

Bits 2 through bit 15 of this register are not used. Bit 1 indicates an external interrupt existing if the content of bit 1 is "1". See Chapter 3, Register Description for more information of this Interrupt Register.

IRQ* will be valid whenever the external interrupt occurs.

Figure 2-4 shows the timing for an interrupt acknowledge cycle.

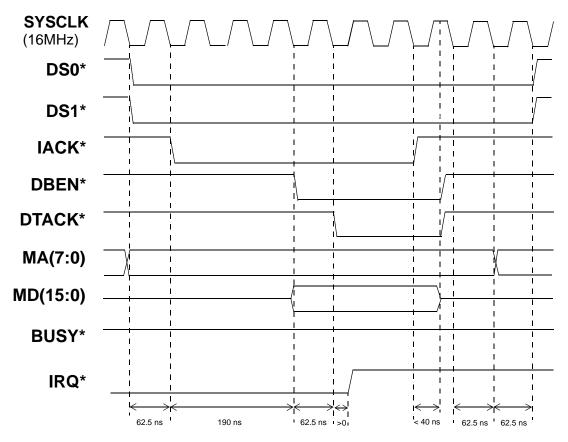


Figure 2-4. Timing for Interrupt Acknowledge Cycle

Program Example

The following program example demonstrates how to access the registers on the HP E2259A. The example uses the VXIplug&play register reads and writes.

The example programs were developed with the ANSI C language using the HP VISA extensions. The programs were written and tested in Microsoft[®] Visual C++ but should compile under any standard ANSI C compiler.

To run the programs you must have the HP SICL Library, the HP VISA extensions, and an HP 82340 or 82341 HP-IB module installed and properly configured in your PC. An HP E1406 Command Module is required for the first program. The HP E2259A must be installed in an HP E2251A Carrier for access to the A16 VXI registers.

The example programs reset the HP E2259A Breadboard M-Module. It then:

- Reads the ID, Device Type, Status, and A24 Memory Offset Registers.
- Writes a value to the I/O Register to output data on BC0 BC15,
- Writes a value to the WP0 Register to output data on BC0 BC15,
- Reads a value from the I/O Register to input data on TR0 TR15,
- Reads a value from the RP0 Register to input data on TR0 TR15.

```
#include <visa.h>
#include <stdio.h>
#include <stdlib.h>
ViSession viRM,m mod;
int main()
unsigned short id reg,dt reg;
                                             /* ID & Device Type Registers */
unsigned short stat reg, a24 offset;
                                             /* Status & A24 Offset Reg */
short value:
                                             /* register variable */
ViStatus errStatus;
                                             /*Status from each VISA call*/
   /* Open the default resource manager */
errStatus = viOpenDefaultRM ( &viRM);
if (VI_SUCCESS > errStatus){
  printf("ERROR: viOpenDefaultRM() returned 0x%x\n",errStatus);
  return errStatus;}
   /* Open the M-Module instrument session */
errStatus = viOpen(viRM,"GPIB-VXI0::8",VI_NULL,VI_NULL,&m_mod);
if (VI_SUCCESS > errStatus){
  printf("ERROR: viOpen() returned 0x%x\n",errStatus);
  return errStatus;}
```

```
/* read and print the module's ID Register */
errStatus = viln16(m_mod,VI_A16_SPACE,0x00,&id_reg);
if (VI_SUCCESS > errStatus){
  printf("ERROR: viln16() returned 0x%x\n",errStatus);
   return errStatus;}
printf("ID register = 0x\%4X\n", id_reg);
    /* read and print the module's Device Type Register */
errStatus = viln16(m mod,VI A16 SPACE,0x02,&dt reg);
if (VI_SUCCESS > errStatus){
   printf("ERROR: viln16() returned 0x%x\n",errStatus);
  return errStatus;}
printf("Device Type register = 0x\%4X\n", dt_reg);
    /* read and print the module's Status Register */
errStatus = viln16(m_mod,VI_A16_SPACE,0x04,&stat_reg);
if (VI_SUCCESS > errStatus){
  printf("ERROR: viln16() returned 0x%x\n",errStatus);
  return errStatus;}
printf("Status register = 0x%hx\n", stat_reg);
    /* read and print the module's A24 Offset Register */
errStatus = viln16(m_mod,VI_A16_SPACE,0x06,&a24_offset);
if (VI_SUCCESS > errStatus){
   printf("ERROR: viOpen() returned 0x%x\n",errStatus);
   return errStatus;}
printf("A24 Offset register value = 0x\%hx\n", a24 offset);
    /* Write a value of AA to I/O Register, Addr 0x14 */
errStatus = viOut16(m_mod,VI_A24_SPACE,0x14,0xAA);
if (VI_SUCCESS > errStatus){
   printf("ERROR: viOut16() returned 0x%x\n",errStatus);
   return errStatus;}
    /* Write a value of FF to WP0 Register, Addr 0x20 */
errStatus = viOut16(m_mod,VI_A24_SPACE,0x20,0xFF);
if (VI SUCCESS > errStatus){
  printf("ERROR: viOut16() returned 0x%x\n",errStatus);
   return errStatus;}
    /* Read the value from I/O Register, Addr 0x14 */
errStatus = viln16(m_mod,VI_A24_SPACE,0x14,&value);
if (VI_SUCCESS > errStatus){
   printf("ERROR: viOut16() returned 0x%x\n",errStatus);
   return errStatus;}
printf("0x14 register value = 0x\%hx\n", value);
```

```
/* Read the value from WP0 Register, Addr 0x20 */
errStatus = viIn16(m_mod,VI_A24_SPACE,0x20,&value);
if (VI_SUCCESS > errStatus){
  printf("ERROR: viOut16() returned 0x%x\n",errStatus);
   return errStatus;}
printf("0x20 register value = 0x%hx\n", value);
    /* Close the M-Module Instrument Session */
errStatus = viClose (m_mod);
if (VI_SUCCESS > errStatus) {
   printf("ERROR: viClose() returned 0x%x\n",errStatus);
   return 0;}
    /* Close the Resource Manager Session */
errStatus = viClose (viRM);
if (VI_SUCCESS > errStatus) {
   printf("ERROR: viClose() returned 0x%x\n",errStatus);
   return 0;}
return VI_SUCCESS;
}
```

Resetting the Module

There are two ways to reset the module and your own external circuitry. The CRST* signal line is available on J102 which is available to reset your circuitry (active low).

Hardware Reset

Whenever you apply power to the system, the HP E2259A breadboard module will also be reset. This pulses the CRST* line low.

Software Reset

You can also write a "1" to bit 0 of the Control Register (address 04h in A16 memory, refer to Chapter 3 for details). This will reset the M-Module and pulse the CRST* line. You must write a "0" to bit 0 of the Control Register after the reset is finished.

Using the Power Supplies

Each power supply available for use by external circuits is protected by a positive-temperature-coefficient thermistor. When maximum current through the thermistor is reached, it heats up, and its resistance increases significantly thereby limiting the current; the thermistor acts like a resettable fuse. Table 2-4 lists the power supplies, thermistor protection reference designator (silkscreened on PC board), and the maximum current.

Table 2-4. HP E2259A Power Supply Protection

	Thermistor Ref. Designator	Maximum Current	Connector	Application
+5VDC Supply	F201	1000mA	J102	Main power source for all systems. Used for supplying power to logic device.
+12VDC Supply	F200	200mA	Near J102	General purpose power for switching power convertors, analog devices and disc drives.
-12VDC Supply	F202	200mA	Near J102	General purpose power for analog devices and disc drives. Not recommended for power convertors.

Application Example

This section contains a simplified example application using the breadboard module as an 8-channel Form-C Relay module. See Figure 2-6. You must supply the relay driver IC, flyback protection, etc. These have been omitted from the drawing for simplification.

Relay Selection

The I/O Register is used as the interface. To open one specific relay, you need to WRITE a "0" to the bit of the I/O Register which corresponds to that relay. To close a channel, you need to write a "1" to the corresponding I/O Register bit.

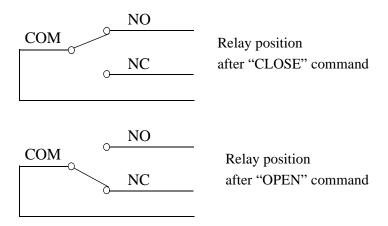
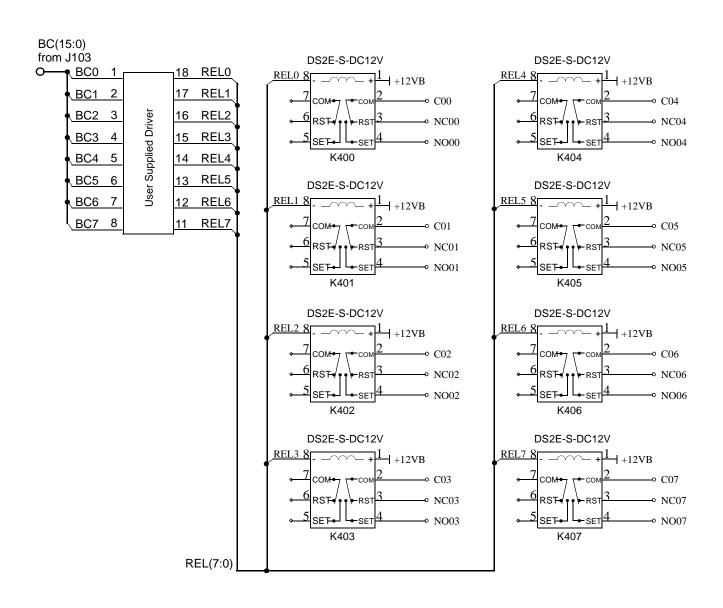


Figure 2-5. Write a "1" or "0" to the Register Bit to Close/Open the Relay

The status of all relays must be specified simultaneously. To change just one relay, it is necessary to change the corresponding bit and send the entire pattern again.



The 16-bit I/O Register of HP E2259A is used to control and readback 8 Form-C Relays.

Figure 2-6. Using the Breadboard as an 8 channel Form C Relay Module

Chapter 3

Register Descriptions

About This Chapter

This chapter contains register addressing information; it also provides the register description of HP E2259A Double-Wide Breadboard M-Module. Chapter contents include:

Note

Most of the descriptions in this chapter assume the HP E2259A is installed in an HP E2251A Carrier. The Carrier provides access to the VXI registers.

Register Addressing in the VXIbus Environment

Logical Address

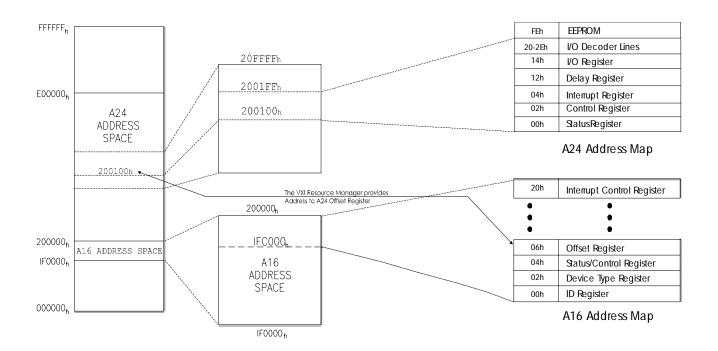
Each module in a VXIbus (VXI) system, whether VXI or M-Module, must have a unique logical address. The HP E2251 Carrier provides a logical address for each installed M-Module. Refer to the HP E2251 Installation and Getting Started Guide for details (if you are using a different carrier, refer to that carrier's documentation for register-based addressing information).

A16/A24 Memory Mapping

The VXI Specification allows for only 64 bytes of address space in A16 memory. However, the M-Module Specification defines 256 bytes of address space. To resolve this conflict, the HP E2251 Carrier provides two memory segments for each installed M-Module. The first is in the VXI A16 memory space and contains the standard VXI registers. The second memory segment is in the VXI A24 memory space and contains all other M-Module registers (these registers are described starting on Page 41). Figure 3-1 shows the A16/A24 mapping for a typical M-Module.

Note

The M-Module's ID word (from the ID EEPROM) is mapped into the VXI Manufacturer ID Register at address 00_h and the M-Module's VXI Device Type word is mapped into the VXI Device Type Register at address 02_h



* Base Address = $1FC000_{16}$ + (Logical Address * 64)₁₆ or $= 2,080,768_{10} + (Logical Address*64)_{10}$

A16 Register Address = Base Address + Register Offset

For M-Modules, the Register Address is Computed as: Base Address = Value in Offset Register Register Address = Base Address Combines the Register Offset (A24 address space)

For Example, in above case, the I/O Register Address is: I/O Register Address = $200100_{16} + 14_{16} = 200114_{16}$ or $= 2.097.408_{10} + 20_{10} = 2.907.428_{10}$

Figure 3-1. A16/A24 Memory Mapping

Determining a Module's A16 Base Address

To access a register in A16 memory, you must specify a hexadecimal or decimal register address. This address consists of a base address plus a register offset. The A16 base address depends on whether or not you are using an HP E1406 Command Module.

A16 Address Space **Inside the Command** Module

When using an HP E1406 Command Module, the base address is computed as:

$$1FC000_h + (LADDR_h \cdot 40_h)$$
or (decimal)
$$2,080,768 + (LADDR \cdot 64)$$

Where:

 $1FC000_h$ (2,080,768) is the A16 starting address LADDR is the module's logical address

40_h (64) is the number of address bytes allocated per module

For example, if the M-Module has a logical address of 78_h (120) the A16 base address becomes:

$$1FC000_h + (78_h \cdot 40_h) = 1FC000_h + 1E00_h = 1FDE00_h$$

or (decimal)
 $2,080,768 + (120 \cdot 64) = 2,080,768 + 7680 = 2,088,448$

A16 Address Space Outside the Command Module

When an HP E1406 Command Module is <u>not</u> part of your system, the base address is computed as:

$$C000_h + (LADDR_h \cdot 40_h)$$

or (decimal)
 $49,152 + (LADDR \cdot 64)$

Where:

C000_h (49,152) is the A16 starting address LADDR is the module's logical address 40_h (64) is the number of address bytes allocated per module

For example, if the M-Module has a logical address of 78_h (120) the A16 base address becomes:

$$C000_h + (78_h \cdot 40_h) = C000_h + 1E00_h = DE00_h$$

or (decimal)
 $49,152 + (120 \cdot 64) = 49,152 + 7680 = 56,832$

Addressing A16 Registers

As shown in Figure 3-1, VXI registers for an M-Module are mapped into A16 address space by the HP E2251 Carrier. To access one of these registers, add the A16 base address to the register offset. For example, an M-Module's VXI Status/Control Register has an offset of 04_h. To access this register (assuming the system does not have an HP E1406 Command Module), use the register address:

$$1FDE00_h + 04_h = 1FDE04_h$$
or (decimal)
2,088,488 + 4 = 2,088,452

Addressing A24 Registers

As shown in Figure 3-1, most of the registers for an M-Module are mapped into A24 address space. To access one of these registers:

- Obtain the A24 base address by reading the VXI Offset Register (06_h) in A16 memory.
- 2. Add the A24 base address to the register offset (see Table 3-2).

For example, if the A24 base address is 200100_h , to access the Output Register (10_h):

$$200100_{\rm h} + 10_{\rm h} = 200110_{\rm h}$$

or (decimal) 2,097,408 + 16 = 2,097,424

Program Example

The following sample program demonstrates how to write to and read from registers on the HP E2259A. The program was developed with the ANSI C language using the HP VISA extensions. The program was written and tested in Microsoft Visual C++ but should compile under any standard ANSI C compiler.

To run the program you must have the HP SICL Library, the HP VISA extensions, and an HP 82340 or 82341 HP-IB module installed and properly configured in your PC. An HP E1406 Command Module provides direct access to the VXI backplane. The HP E2259A must be installed in an HP E2251A Carrier for access to the A16 VXI Registers.

```
#include <visa.h>
#include <stdio.h>
#include <stdlib.h>
ViSession viRM,m_mod
int main()
  ViStatus errStatus:
                                            /*Status from each VISA call*/
                                            session*/
/* Open the default resource manager */
  errStatus = viOpenDefaultRM (&viRM);
  if(VI_SUCCESS > errStatus){
    printf("ERROR: viOpenDefaultRM() returned 0x%x\n",errStatus);
    return errStatus;}
/* Open the M-Module instrument session */
errStatus = viOpen(viRM,INSTR_ADDR, VI_NULL,VI_NULL,&m_mod);
  if(VI_SUCCESS > errStatus){
    printf("ERROR: viOpen() returned 0x%x\n",errStatus);
    return errStatus;}
  /* read and print the module's ID Register */
errStatus = viln16(m_mod,VI_A16_SPACE,0x00,&id_reg);
  if (VI_SUCCESS > errStatus){
    printf("ERROR: viln16() returned 0x%x\n",errStatus);
    return errStatus;}
    printf("ID register = 0x\%hx\n", id_reg);
  /* read and print the module's Device Type Register */
errStatus = viln16(m_mod,VI_A16_SPACE,0x02,&dt_reg);
  if (VI_SUCCESS > errStatus){
    printf("ERROR: viln16() returned 0x%x\n",errStatus);
    return errStatus;}
  printf("Device Type register = 0x\%hx\n", dt reg);
  /* read and print the module's Status Register */
errStatus = viln16(m_mod,VI_A16_SPACE,0x04,&stat_reg);
  if (VI_SUCCESS > errStatus){
    printf("ERROR: viln16() returned 0x%x\n",errStatus);
    return errStatus;}
```

```
printf("Status register = 0x\%hx\n", stat reg);
/* read and print the module's A24 Offset Register */
errStatus = viln16(m_mod,VI_A16_SPACE,0x06,&a24_offset);
  if(VI_SUCCESS > errStatus){
  printf("ERROR: viOpen() returned 0x%x\n",errStatus);
    return errStatus;}
  printf("A24 Offset register value = 0x%hx\n", a24_offset);
  /* set the BUSY Delay Timer to 15mS (see Busy Timer) */
  errStatus = viOut16 (m mod,VI A24 SPACE,0x12,0x1D6);
  if (VI_SUCCESS > errStatus){
    printf("ERROR: viOut16() returned 0x%x\n",errStatus);
    return errStatus;}
  /* Output a Value of 5 on BCn Data Lines */
  errStatus = viOut16 (m_mod,VI_A24_SPACE,0x14,0x05);
  if (VI_SUCCESS > errStatus){
    printf("ERROR: viOut16() returned 0x%x\n",errStatus);
    return errStatus;}
/* Close the M-Module Instrument Session */
  err_status = viClose (m_mod);
  if (VI SUCCESS > errStatus) {
    printf("ERROR: viClose() returned 0x%x\n",errStatus);
    return 0:}
/* Close the Resource Manager Session */
  err status = viClose (viRM);
  if (VI_SUCCESS > errStatus) {
    printf("ERROR: viClose() returned 0x%x\n",errStatus);
    return 0;}
  return VI_SUCCESS;
```

Register Descriptions

There are two sets of registers in the memory window of M-Modules. One is the same as a standard VXIbus instrument register in A16 address space (provided by the HP E2251A Carrier), the other is in A24 address space.

Registers in A16 Address Space

The five registers including the VXI ID Register, VXI Device Type Register, Status/Control Register, Offset Register, Interrupt Control These register are mapped in A16 address space.

Table 3-1 lists the five registers in the A16 memory space. The following paragraphs describe each register.

Table 3-1. VXIbus A16 Memory Instrument Registers

Address Mapping	Registers
00 _h	VXI ID Register
02 _h	VXI Device Type Register
04 _h	VXI Status/Control Register
06 _h	VXI Offset Register
20 _h	M-Module Interrupt Control Register

VXI ID Register

The ID Register is a read only register at address 00_h and provides instrument identification information.

b+00 _h	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Write							Un	defined								
Read	Device	Class	Add Spa						Ma	anufact	urer ID					

- **Device Class:** this bit should always be 11 indicating a register-based device.
- Address Space: 00 indicating A16/A24 device
- Manufacturer ID: 4095 (decimal) for Hewlett-Packard M-Modules

VXI Device Type Register

The Device Type Register is a read only register at address 02_h. Reading this register returns a unique identifier for each M-Module.

b+02 _h	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Write		Undefined														
Read		Required Memory M-Module Model Code														

- **Required Memory**: F_h indicating 256 byte block required.
- M-Module Model Code: 258_h for the HP E2259A.

VXI Status/Control Register

The Status/Control Register is a read/write register (address 04_h) that controls the module and indicates its status.

b+04 _h	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Write (Control)	A24 Enable					R	eser	ved							Sysfail Inhibit	Reset
Read (Status)	A24 Active	MODID*	MODID* M-Module Device Dependent Ready Passed												Device D	ependent

- **A24 Enable.** A 1 in this bit means access to the devices A24 registers is enabled.
- Sysfail Inhibit. Writing a 1 disables the M-Module from driving the SYSFAIL* line.
- **Reset.** Writing a 1 then a 0 to this bit forces the M-Module to reset.
- A24 Active. A 1 in this bit indicates the M-Module's registers in A24 memory space can be accessed. Default = 1.
- MODID*. A 1 in this bit indicates that the M-Module is not selected via the P2 MODID line. A 0 indicates the M-Modules is selected by a high state on the P2 MODID line.
- **Ready.** A 1 in this bit indicates that the M-Module is ready to accept commands. A 0 indicates the M-Module is busy and not ready to accept commands.
- Passed. A 1 in this bit indicates the M-Module passed its self test successfully. A 0 indicates the M-Module is either executing or has failed its self test.

VXI Offset Register

The Offset Register (address 06_h) contains the value of the base address for accessing registers in the A24 address space.

b+06 _h	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Write		Register written to by VXI Resource Manager. Do not attempt to write to this register.														
Read				A24 Sp	ace Bas	e address	s for tho	se M-N	1odules	needin	g A24 r	nemory	′			

Interrupt Selection Register

The Interrupt Selection Register (address 20_h) specifies which VXI interrupt line the M-Module will use. M-Modules may generate interrupts to indicate that a SCPI command has completed. These interrupts are sent to and acknowledged by the HP Command Module or other system controller via one of seven VXI backplane interrupt lines. Different controllers treat the interrupt lines differently, and you should refer to your controller's documentation to determine how to set the interrupt level. HP Command Modules configured as VXI Resource Managers treat all interrupt lines as having equal priority. For interrupters using the same line, priority is determined by which slot they are installed in; lower-numbered slots have higher priority than higher-numbered slots. HP Command Modules service line 1 by default, so it is normally correct to leave the interrupt level set to the factory default of IRQ1.

b+20 _h	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Write		Reserved Reserved												VXII	nterrupt	t Line
Read														VXI II	nterrupt 0	Line 1

If your controller's documentation instructs you to change the interrupt level, you need to specify the level in the VXI Interrupt Selection Register. To cause the M-Module to interrupt on one of the VXI interrupt lines, write to the appropriate bits (refer to table below). To disable the module's interrupt, set the bits to 000. Selecting other than the default interrupt line 1 is not recommended. Reading the default value of this register returns the value $XXX9_h$.

Bits 2 - 0	Selected Interrupt Line
000	NONE (Interrupt Disabled)
001	IRQ1 (default)
010	IRQ2
011	IRQ3
100	IRQ4
101	IRQ5
110	IRQ6
111	IRQ7

M-Module specifications define three types of interrupts. The INT bit (bit 3) determines which M-Module interrupt style is supported. If INT is set to a 0, the M-Module supports interrupt types A and B. If INT is set to a 1, the M-Module supports interrupt type C (this is the default).

Type A Interrupts The interrupting M-Module removes the interrupt request upon a register access (software method) to the interrupting M-Module (such as reading the Status Register). DTACK* is not asserted during interrupt acknowledge.

Type B Interrupts The interrupting M-Module removes the interrupt request via a hardware method (on IACK* going low) but provides no vector information for the interrupt. This is the same as Type C interrupts except that no vector is supplied and DTACK* is not asserted.

Type C Interrupts The interrupting M-Module removes the interrupt request via a hardware method and provides an interrupt vector on the data bus and DTACK* is asserted during the interrupt acknowledge cycle. The M-Module removes the interrupt request by IACK* going low.

In VXI specifications however, only two types of interrupts are defined; RORA (Release on Register Access) and ROAK (Release on Acknowledge). The HP E2251A Carrier converts M-Module Type A interrupts to RORA and Types B and C interrupts to ROAK (default).

RORA Interrupts The interrupting device provides its logical address on the data bus (MD0 - MD7) during the interrupt acknowledge cycle that was initiated in response to its interrupt request. It does not remove the interrupt request until its Status/Control register is accessed.

ROAK Interrupts The interrupting device removes the interrupt request upon the presence of a properly addressed interrupt acknowledge cycle and provides its logical address on the data bus (MD0 - MD7). A cause/status byte is also placed on the data bus (MD15 - MD8)

Registers in A24 Address Space

There are several registers including a Status Register, Control Register, Interrupt Register, Delay Register, the Input/Output Register, and the Read/Write Decoder registers plus an EEPROM in A24 address space of the Breadboard Module. The Module also provides a set of decoder lines located from 20_h through $2E_h.$ Table 3-2 lists the address mapping

Table 3-2. HP E2259A Registers in A24 Memory

Address	Registers
FE _h	EEPROM
30 _h - FC _h	Reserved
20 _h - 2E _h	Read/Write Decoder Registers
16 _h - 1E _h	Reserved
14 _h	I/O Register
12 _h	Delay Register
10 _h	Reserved
(06 _h - 0F _h)	Reserved
04 _h	Interrupt Register
02 _h	Control Register
00 _h	Status Register

A24 Status Register The offset of Status Register is 00_h . It is a Read only register

b+00 _h	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Write		Reserved														
Read				Reser	ved				Busy*		R	eserve	ed		EIRQX	RIRQX

• BUSY*: 0-Circuit is busy (not stable yet).

EIRQX: 1-External interruptRIRQX:1-Circuit interrupt.

Control Register The offset of Control Register is 02_h. It is a Read/Write register

b+02 _h	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Write						Rese	ved							EENABLE	RENABLE	Soft Reset
Read						Rese	ved							EENABLE	RENABLE	Soft Reset

- EENABLE: 1 Enable External interrupt;
- RENABLE: 1 Enable circuit interrupt (After BUSY timer);
- Soft Reset: 1 Soft Reset HP E2259A.

When power-on or reset, all bits of Control Register are set to zero.

Interrupt Register The offset of Interrupt Register is 04_h. It is a Read only register.

b+04 _h	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Write		Reserved														
Read		Reserved RIRQX													RIRQX	

• RIRQX: 1 - Circuit interrupt

BUSY Delay Timer Register

The offset of BUSY Delay Timer Register is 12_h. It is a write only register. The value of this register determines the delay time between command execution and asserting interrupt. The delay time is determined by the formula:

Delay Time = (Register value + 1) * 0.031875 ms

where: **Register value** can be from 0000_h through FFFF_h

• The default value of **Delay Time** is 13 ms (register value = 407_{10} or $197_{\rm h}$).

I/O Register

The offset of the Input/Output Register is 14_h. Reading this Register will get the status of TR0 - TR15 lines. Writing to this Register will latch MD15-MD0 into two 74ACTQ273 latches (BC0 - BC15).

b+14 _h	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Write		Output Bits (BC15 - BC0)														
Read						Ir	put Bits	s (TR15	5 - TR0)							

• Writing a 1 sets bit high; writing a 0 sets bit low.

Read/Write Decoder Lines Registers

Writing a value to one of these registers asserts the corresponding WP line. Reading from one of these registers asserts the corresponding RP line. These decoder lines can be used to expand the I/O registers. Refer to Chapter 2 for timing information and using these registers.

b+20 _{h -} b+2E _h	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Write	Output Bits (BC15 - BC0)															
Read	Input Bits (TR15 - TR0)															

Table 3-3 lists the Read/Write Decoder Register Addresses and the corresponding WP and RP lines.

Table 3-3. Read/Write Decoder Lines and Register Addresses

WP / RP Line	Register Address	WP / RP Line	Register Address
WP0/ RP0	20 _h in A24 Memory	WP4 / RP4	28 _h in A24 Memory
WP1 / RP1	22 _h in A24 Memory	WP5 / RP5	2A _h in A24 Memory
WP2 / RP2	24 _h in A24 Memory	WP6 / RP6	2C _h in A24 Memory
WP3 / RP3	26 _h in A24 Memory	WP7 / RP7	2E _h in A24 Memory

EEPROM

There is an EEPROM on the Breadboard for identification. The offset of it is FE_h in A24 address space. The size of the EEPROM is 64 words (128 byte) and all the characteristics of M-Module are stored in it. The first 16 words (0 through 15) are defined in the M-Module Specifications; words 16 - 63 are described in Table 3-4.

Table 3-4. EEPROM Contents

Word #	Description	Value
0	Sync code	5346 _h
1	module number (binary code)	1659 _h
2	revision number (binary code)	0001
3	module characteristics	1868 _h
4 - 7	reserved	
8 - 15	User-defined	
16	VXI Sync code	ACBA _h (2's complement of 0x5346)
17	VXI-ID	CFFF _h
18	VXI-Device Type	F258 _h
19 - 31	Reserved	
32 - 47	User-defined	
48 - 63	Reserved	

Appendix A HP E2259A Specifications

The HP E2259A Double-Wide Breadboard Module complies with the Mezzanine Concept M-Module Specification.

The specifications of HP E2259A are listed in the following table:

ITEM	SPECIFICATIONS
User Component Area	70 cm ² (10.86 in ²) occupying two slots.
Grid Hole Spacing	2.54 mm (0.1 in.)
Grid Hole Inside Diameter	1.17 mm (0.046 in.)
Maximum Component Height	5.3 mm (0.21 in.) above board in Region A, 10.5 mm (0.42 in.) above board in Region B. Refer to "HP E2259A Connectors Layout" on page 13.
Maximum Lead Length	1.2 mm (0.078 in.) below board. Refer to "HP E2259A Connectors Layout" on page 13.
Maximum Power Dissipation (per module)	Determined by mainframe cooling and/or HP E2251A Cooling Capacity. Do not exceed 40 Watts.
Power Supplies	+5 VDC ±5% @ 100mA maximum +12 VDC ±5% @ 200mA maximum -12VDC ±5% @ 200mA maximum
Connectors	Two 44-pin connectors (user interface), Two 40-pin connectors to the carrier

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